L Number	Hits	Search Text	" <u>" - </u>	
29	3489		DB	Time stamp
30	307	136/200-242.ccls. and via	USPAT	2003/03/04 09:17
31	0	150,200 242.0013. and Via	USPAT	2003/03/04 09:17
32	Ö		USPAT	2003/03/04 09:34
33	l i		USPAT	2003/03/04 09:34
34	į ō	("19 and thermoelectric").PN.	USPAT	2003/03/04 09:35
35	0	To and enermoetectic).PN.	USPAT	2003/03/04 09:35
44	2	136/200-242.ccls. and (wafer adj1 bonding)	USPAT	2003/03/04 09:35
45	Ī	("5598031").PN.	USPAT	2003/03/04 10:06
46	1	("6162659").PN.	USPAT	2003/03/04 10:14
47	1300	wafer adj bonding	USPAT	2003/03/04 10:14
48	0	257/930 and (wafer adj bonding)	USPAT	2003/03/04 10:26
49	131	257/930 and (water adj bonding)	USPAT	2003/03/04 10:27
50	0	257/930 and (wafer adj bonding)	USPAT	2003/03/04 10:27
51	9038	257/712 amd (wafer adj bonding)	USPAT	2003/03/04 10:27
52	2021	257/712 and (water adj bonding)	USPAT	2003/03/04 10:28
53	6	257/717 and (wafer adj bonding)	USPAT	2003/03/04 10:29
54	6	257/722 and (wafer adj bonding)	USPAT	2003/03/04 10:31
55	2	257/719 and (wafer adj bonding)	USPAT	2003/03/04 10:32
56	6	257/713 and (wafer adj bonding)	USPAT	2003/03/04 10:41
57	44	257/930 and bonding	USPAT	2003/03/04 10:42
58	445	257/950 and bonding	USPAT	2003/03/04 10:44
59	2	257/\$.ccls. and (wafer adj bonding)	USPAT	2003/03/04 10:55
1		(257/\$.ccls. and (wafer adj bonding)) and heatsink	USPAT	2003/03/04 10:45
60	2			
61	4	136/200-242.ccls. and (wafer adj bonding) (wafer adj bonding) and heatsink	USPAT	2003/03/04 10:48
62	332	136/204 .	USPAT	2003/03/04 10:49
63	572	136/201	USPAT	2003/03/04 10:58
64	95	136/201 and bonding	USPAT	2003/03/04 10:59
65	443	136/200_242 cols and	USPAT	2003/03/04 11:16
66	156	136/200-242.ccls. and ceramic	USPAT	2003/03/04 11:16
	130	(136/200-242.ccls. and ceramic) and semiconductor	USPAT	2003/03/04 11:17
		Semiconductor		

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